

N-Channel Power MOSFET

30V, 88A, 6.1mΩ

FEATURES

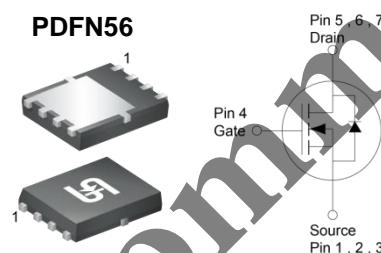
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS

| PARAMETER | VALUE | UNIT |
|-----------------------|-----------------|------|
| V_{DS} | 30 | V |
| $R_{DS(on)}$ (max) | $V_{GS} = 10V$ | 6.1 |
| | $V_{GS} = 4.5V$ | 8.1 |
| Q_g | 9.3 | nC |

APPLICATION

- DC-DC Converters
- Battery Power Management
- ORing FET/Load Switching



Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|------------------------------------------------------------|----------------|--------------|------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current <small>(Note 1)</small> | I_D | 88 | A |
| $T_C = 25^\circ C$ | | 16 | |
| Pulsed Drain Current | I_{DM} | 352 | A |
| Single Pulsed Avalanche Current <small>(Note 2)</small> | I_{AS} | 22 | A |
| Single Pulsed Avalanche Energy <small>(Note 2)</small> | E_{AS} | 72.6 | mJ |
| Total Power Dissipation | P_D | 78 | W |
| $T_C = 125^\circ C$ | | 15.6 | |
| Total Power Dissipation | P_D | 2.6 | W |
| $T_A = 125^\circ C$ | | 0.5 | |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | - 55 to +150 | °C |

THERMAL PERFORMANCE

| PARAMETER | SYMBOL | LIMIT | UNIT |
|----------------------------------------|-----------|-------|------|
| Junction to Case Thermal Resistance | R_{EJC} | 1.6 | °C/W |
| Junction to Ambient Thermal Resistance | R_{EJA} | 48 | °C/W |

Thermal Performance Note: R_{EJA} is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. R_{EJA} is guaranteed by design while R_{ECA} is determined by the user's board design.

| ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ C$ unless otherwise noted) | | | | | | |
|-------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|---------------|------------|------------|------------|-------------|
| PARAMETER | CONDITIONS | SYMBOL | MIN | TYP | MAX | UNIT |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | BV_{DSS} | 30 | -- | -- | V |
| Gate Threshold Voltage | $V_{GS} = V_{DS}, I_D = 250\mu A$ | $V_{GS(TH)}$ | 1.2 | 1.8 | 2.5 | V |
| Gate-Source Leakage Current | $V_{GS} = \pm 20V, V_{DS} = 0V$ | I_{GSS} | -- | -- | ± 100 | nA |
| Drain-Source Leakage Current | $V_{GS} = 0V, V_{DS} = 30V$ | I_{DSS} | -- | -- | 1 | μA |
| | $V_{GS} = 0V, V_{DS} = 30V$ $T_J = 125^\circ C$ | | -- | -- | 100 | |
| Drain-Source On-State Resistance (Note 3) | $V_{GS} = 10V, I_D = 16A$ | $R_{DS(on)}$ | -- | 5.2 | 6.1 | $m\Omega$ |
| | $V_{GS} = 4.5V, I_D = 16A$ | | -- | 7 | 8.1 | |
| Forward Transconductance (Note 3) | $V_{DS} = 5V, I_D = 16A$ | g_{fs} | -- | 50 | -- | S |
| Dynamic (Note 4) | | | | | | |
| Total Gate Charge | $V_{GS} = 10V, V_{DS} = 15V,$ $I_D = 16A$ | Q_g | -- | 19 | -- | nC |
| Total Gate Charge | $V_{GS} = 4.5V, V_{DS} = 15V,$ $I_D = 16A$ | Q_g | -- | 9.3 | -- | |
| Gate-Source Charge | | Q_{gs} | -- | 3.7 | -- | |
| Gate-Drain Charge | | Q_{gd} | -- | 3.6 | -- | |
| Input Capacitance | $V_{GS} = 0V, V_{DS} = 15V$ $f = 1.0MHz$ | C_{iss} | -- | 1133 | -- | pF |
| Output Capacitance | | C_{oss} | -- | 276 | -- | |
| Reverse Transfer Capacitance | | C_{rss} | -- | 96 | -- | |
| Gate Resistance | $f = 1.0MHz$ | R_g | 0.3 | 1 | 2 | Ω |
| Switching (Note 4) | | | | | | |
| Turn-On Delay Time | $V_{GS} = 10V, V_{DS} = 15V,$ $I_D = 7.5A, R_G = 10\Omega,$ $R_L = 2\Omega$ | $t_{d(on)}$ | -- | 11.6 | -- | ns |
| Turn-On Rise Time | | t_r | -- | 5.8 | -- | |
| Turn-Off Delay Time | | $t_{d(off)}$ | -- | 34.4 | -- | |
| Turn-Off Fall Time | | t_f | -- | 7.8 | -- | |
| Source-Drain Diode | | | | | | |
| Forward Voltage (Note 3) | $V_{GS} = 0V, I_S = 16A$ | V_{SD} | -- | -- | 1.2 | V |
| Reverse Recovery Time | $I_S = 16A,$ $dI/dt = 100A/\mu s$ | t_{rr} | -- | 21 | -- | ns |
| Reverse Recovery Charge | | Q_{rr} | -- | 14 | -- | nC |

Notes:

1. Silicon limited current only.
2. $L = 0.3mH, V_{GS} = 10V, V_{DS} = 25V, R_G = 25\Omega, I_{AS} = 22A$, Starting $T_J = 25^\circ C$
3. Pulse test: Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Switching time is essentially independent of operating temperature.

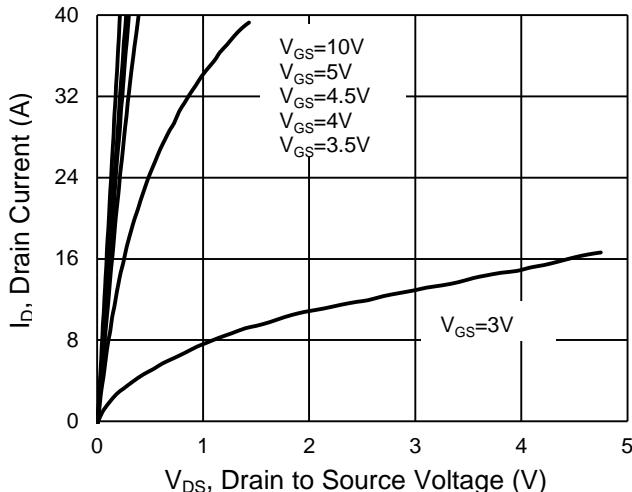
ORDERING INFORMATION

| PART NO. | PACKAGE | PACKING |
|------------------|----------------|---------------------|
| TSM061NA03CR RLG | PDFN56 | 2,500pcs / 13" Reel |

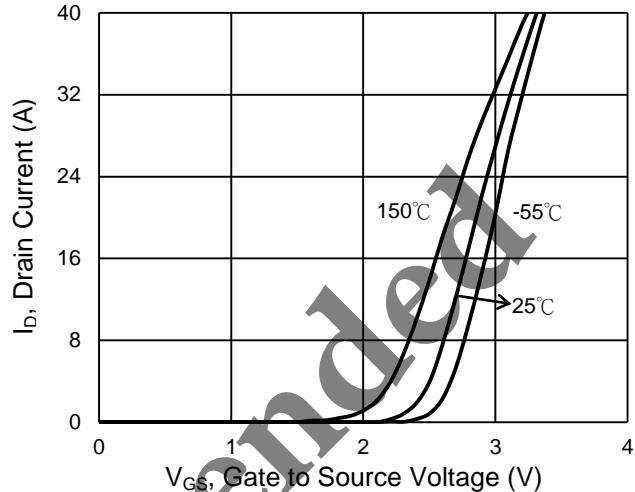
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

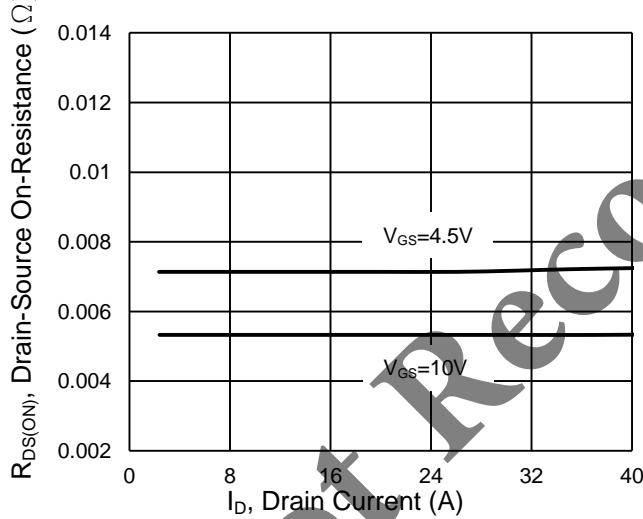
Output Characteristics



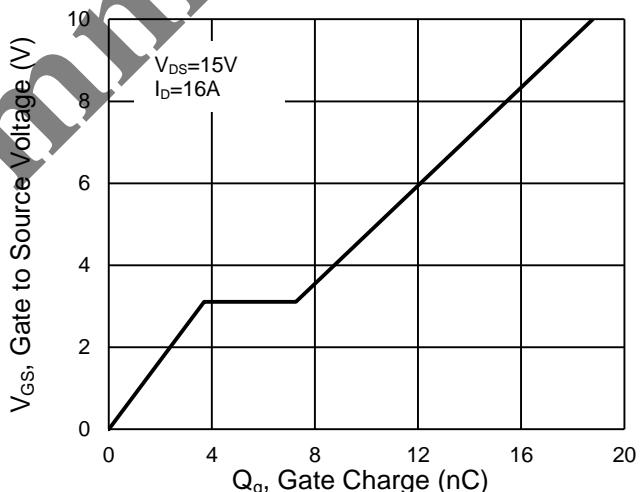
Transfer Characteristics



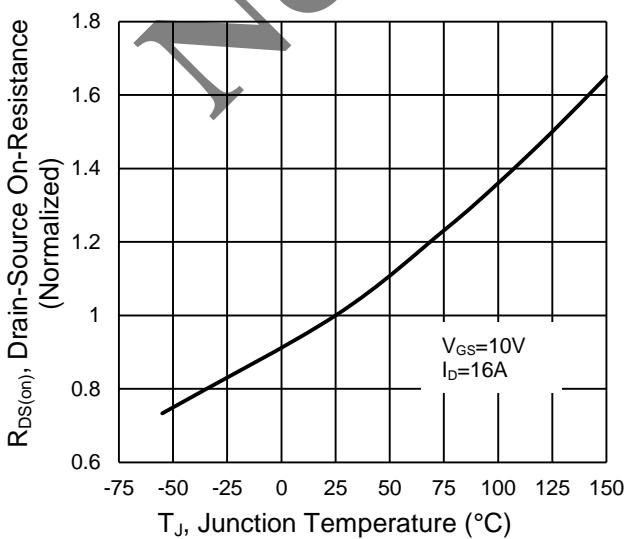
On-Resistance vs. Drain Current



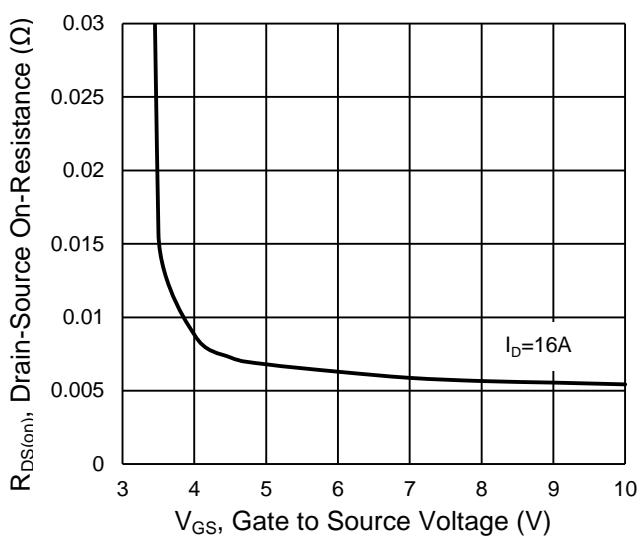
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature

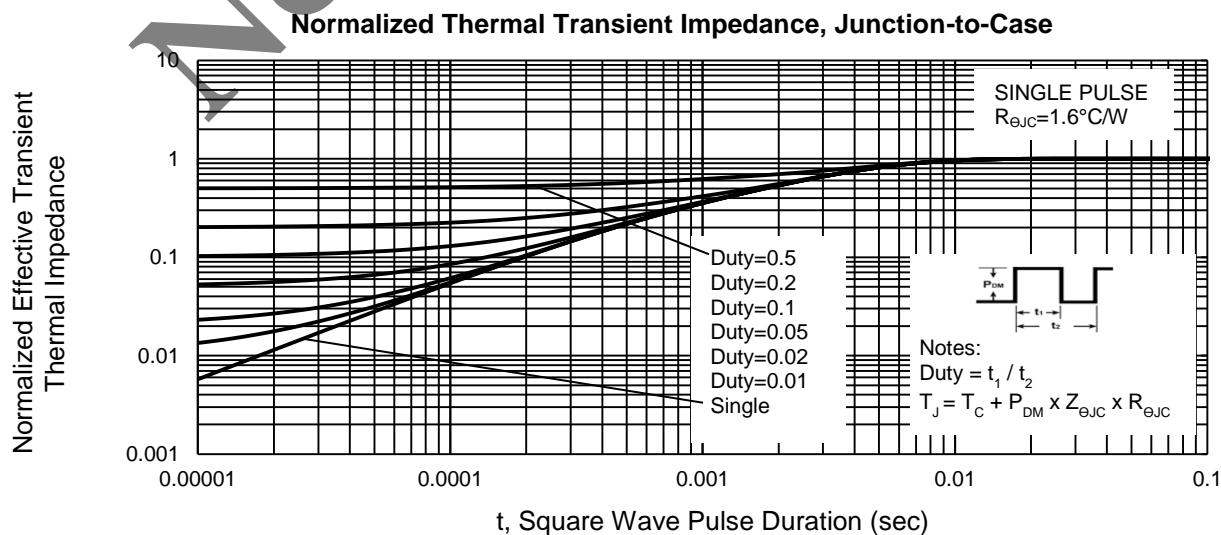
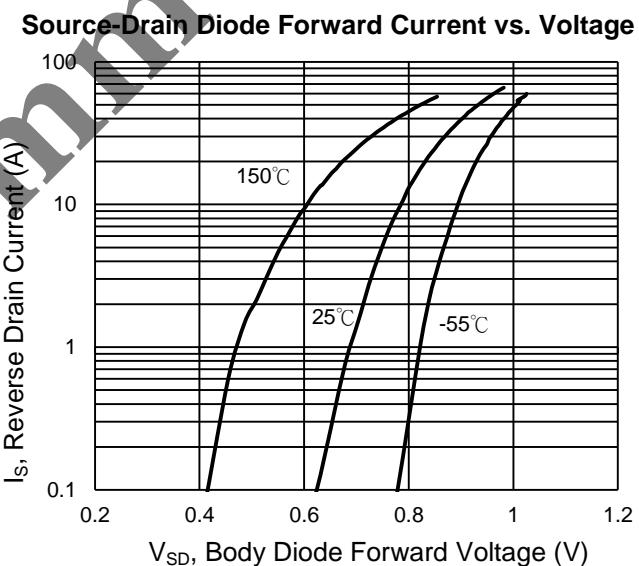
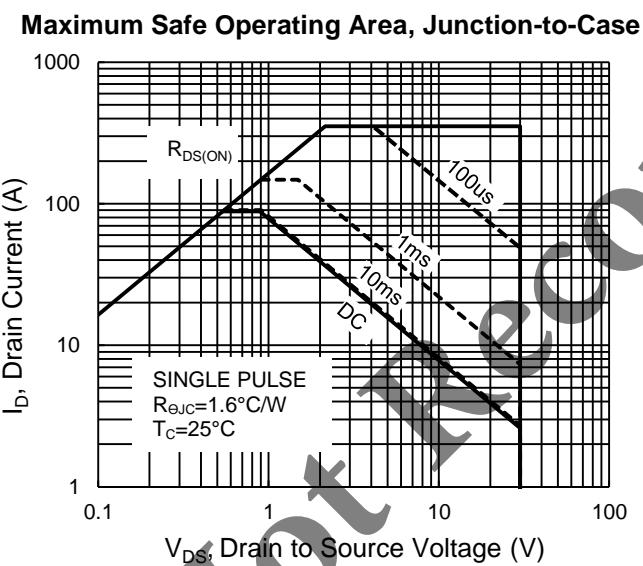
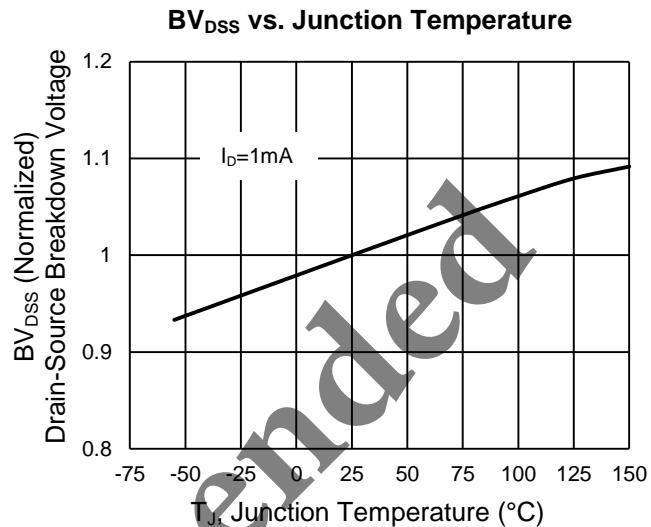
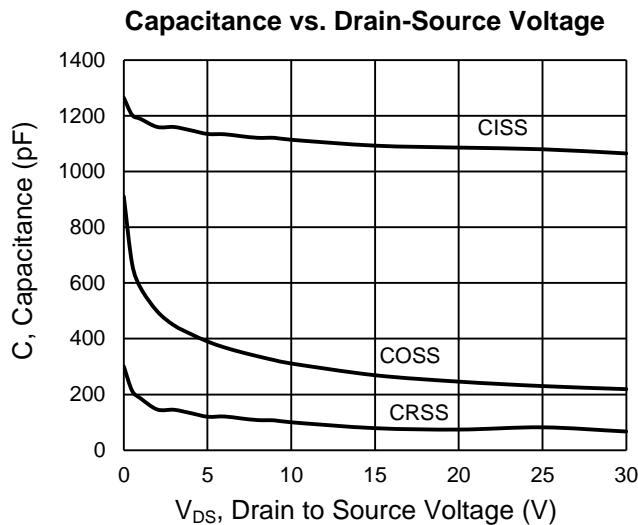


On-Resistance vs. Gate-Source Voltage

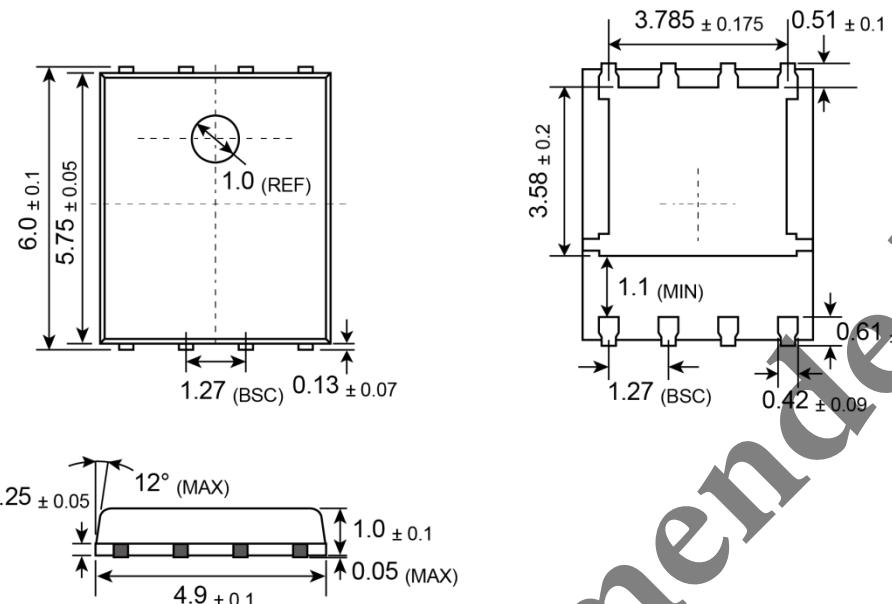
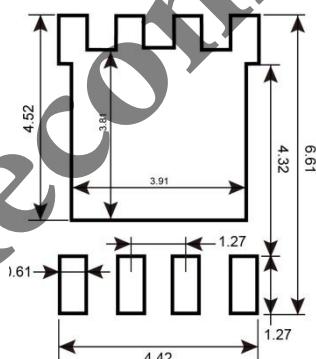


CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

PDFN56

SUGGESTED PAD LAYOUT (Unit: Millimeters)

MARKING DIAGRAM

G = Halogen Free

Y = Year Code

WW = Week Code (01~52)

F = Factory Code

Not Recommended

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